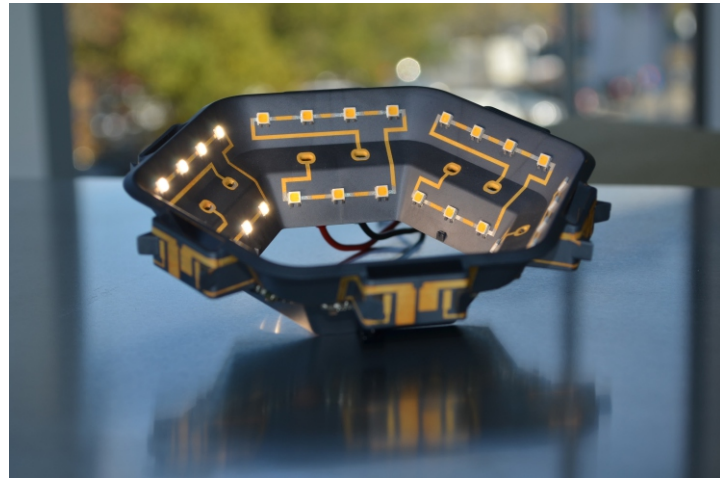


# MID Summit & MID Workshop

21<sup>st</sup> – 22<sup>nd</sup> September 2022

Böblingen (near Stuttgart), Germany



## Invitation

### MID Summit & MID Workshop 2022 as joint event of Hahn-Schickard and 3-D MID e.V.

Hahn-Schickard and the Research Association 3-D MID e. V. will combine the events "MID Summit" and "MID Workshop" this year as a joint industry get-together on September 21st and 22nd in Böblingen (Stuttgart region).

We offer two intensive days around the MID topic with expert presentations from industry and research with many application examples, poster session, trade exhibition and plenty of time for exchange and networking.

In recent years, MID technology has evolved. This is reflected in the change of the name MID from Molded Interconnect Devices to Mechatronic Integrated Devices. New materials and processes have expanded the range of applications and possible functionalization of 3D circuit carriers. Additive manufacturing processes, for example, are opening up new routes for the rapid realization of prototypes and the individualization of products.

Take the opportunity to gain new insights and exchange ideas. Register for the event here: <https://www.3d-mid.de/en/events-1/mid-summit-the-platform-for-mid-technologies/registration/>

If you are interested in presenting your institute or company at the trade exhibition on September 21st with a table top presentation, please feel free to register here (number of slots are limited): <https://www.3d-mid.de/en/events-1/mid-summit-the-platform-for-mid-technologies/registration/>

We are looking forward to your visit!

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für angewandte Forschung e.V.

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### Information

- Wednesday 21<sup>st</sup> – Thursday 22<sup>nd</sup> September 2022
- daily from 9 AM till 5 PM (CEST)
- Al xpress, Röhler Weg 8, 71032 Böblingen, GER
- Hotel Rieth: Single Room 92 € per night



Technical Presentations



Poster Sessions



Trade Exhibition

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## Program

### Wednesday, 21st September

9:30 AM Welcome by Ministerial Council Claus Mayer  
Opening by Prof. André Zimmermann, Hahn-Schickard and Prof. Jörg Franke, 3-D MID e.V.

#### MID Applications

10:00 AM New Applications  
Thomas Hess, HARTING AG

10:30 AM Si-Wafer Replacement and  
MID LDS Transformer  
Dr. Sebastian Bengsch, Ensinger

11:00 AM Metalized-plastic Technology Enabling  
3D Millimeter-wave Components  
Prof. Jan Hesselbarth, Uni Stuttgart - IHF

11:30 AM Advantages of 3D Circuit  
Design in an ECAD Tool  
Christian Röck, Altium

12:00 PM Networking, Exhibition and Poster Session of  
Current Research Projects with Light Snacks

#### New Materials and Technologies

1:00 PM Metallization of Oxide Ceramic Substrates  
via Laserinduced Direct Metallization  
Philipp Ninz, Uni Stuttgart - IFKB

1:30 PM MID Manufacturing: From Plastic  
Granulate to Demonstrator  
Niklas Pieculek,  
FAU Erlangen-Nürnberg - FAPS

2:00 PM 3D Printed Chip Packaging  
Dr. Ashok Sridhar, TNO Holst Centre

2:30 PM Contacting Inkjet-Printed Silver  
Structures and SMD  
Jonas Jäger, Hahn-Schickard

3:00 PM Networking, Exhibition and Poster Session  
of Current Research Projects

4:00 PM General Meeting 3-D MID e.V. alternatively  
Excursion to Hahn-Schickard - Focus on „Digital  
Process Chain for Individualized Microsystems“

7:00 PM Evening Event in the Courtyard  
with Food Truck

### Thursday, 22nd September

9:00 AM Smarter Surfaces for a Smarter Future  
Markus Thamm, Salcon International

9:30 AM Networking and Poster Session of  
Current Research Projects

#### Additive Manufacturing Processes

10:00 AM Retrofit Sensor Technology  
Peter Peetz, IMS Connector Systems

10:30 AM Rapid Prototyping of MID by  
Stereolithographic Printing  
Dr. Hendrik Mohrmann, Contag

11:00 AM Functionalized Otoplastic (MikroBO)  
Hartmut Richter, Audifon

11:30 AM Pad printing electronics – enabling  
the future of 3D connected surfaces  
Aad van der Spuij, Henkel

12:00 PM Networking, Exhibition and Poster Session of  
Current Research Projects with Light Snacks

1:00 PM Workshops on Various Topics  
in Small Groups

3:00 PM Networking, Exhibition and Poster Session  
of Current Research Projects

3:30 PM Presentation of the Results  
from the Workshops

4:00 PM Final Lecture and Farewell  
Prof. André Zimmermann, Hahn-Schickard  
and Prof. Jörg Franke, 3-D MID e.V.